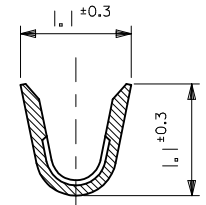
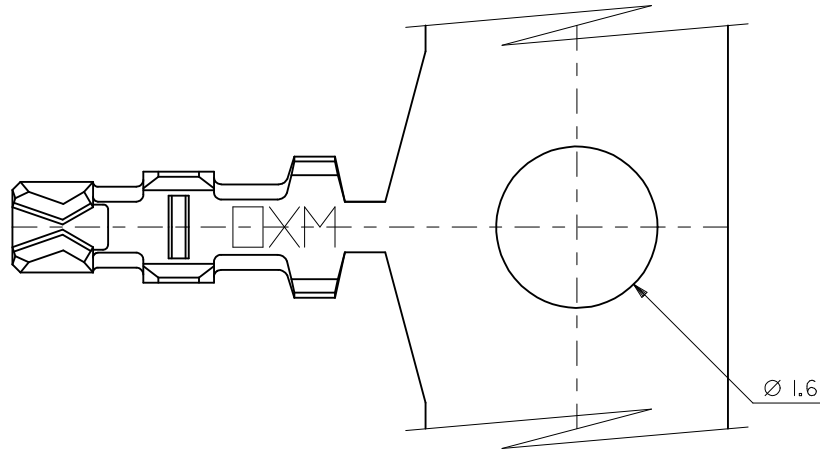
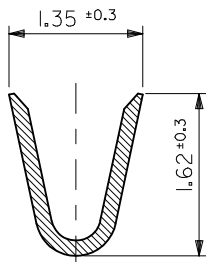


注記
NOTES

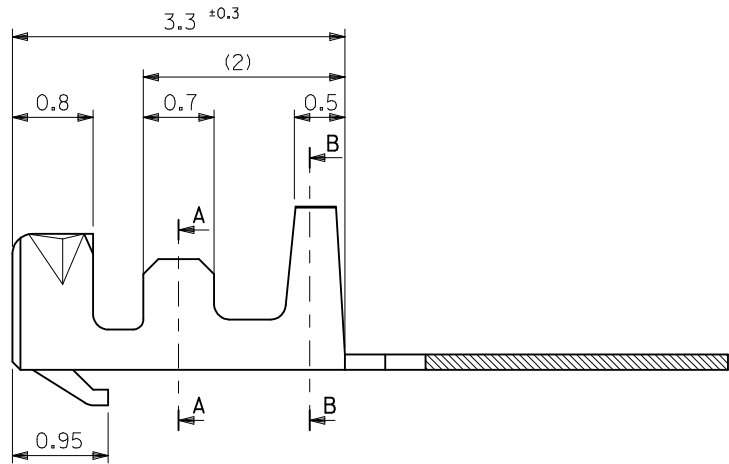
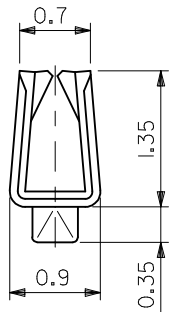
1. 適合ハウジング：51021シリーズ
APPLICABLE HOUSING : 51021 SERIES



SECT. A-A



SECT. B-B



CONTACT AREA: GOLD PLATING (0.38µm MIN.) CRIMP BARREL AREA: TIN PLATING (14µm MIN.) (HEAT TREATED MATTE TIN) UNDERPLATE: NICKEL OVERALL	CHAIN	500798025
PRE-TIN PLATED (HEAT TREATED MATTE TIN) PLATING THICKNESS: 0.94µm MIN.	LOOSE	500798100
	CHAIN	500798000
PLATING	FORM	MATERIAL NO.

MODEL NO. 50079-8***

材料 MATERIAL リン青銅 (t=0.15) PHOSPHOR BRONZE 仕上げ FINISH — 適用電線範囲 WIRE RANGE AWG #26-28 被覆外径 INS. RANGE φ0.5-1.04	REVISED EC NO: J2017-0429 DRWN:SOBARA01 2017/02/15 CHK:DAIDA 2017/02/15 APPR:KANeko 2017/02/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.2	MM ONLY	20:1	METRIC	⊙
		0.25 OVER	0.5 UNDER	±0.2	DRAWN BY	DATE	TITLE	
		0.5 OVER	1.0 UNDER	±0.2	HIRAMOT	92/10/21	PICOBLADE 1.25 CRIMP REC.TERMINAL	
		1.0 OVER	30 UNDER	±0.2	CHECKED BY	DATE	DOCUMENT NO.	
10 OVER	30 UNDER	±0.25	SKUNISHI	98/07/07	SD-50079-001			
30 OVER		±0.3	APPROVED BY	DATE	SHEET NO.			
ANGULAR	±3 °		MFUKUSHI	98/07/07	1 OF 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				A3				